



PATENT
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THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of
Fjelstad et al.

Application No. 09/020,647

Filed: February 9, 1998

For: Methods of Making Compliant
Semiconductor Chip Packages
(As Amended)

Box CPA

Commissioner for Patents
Washington, D.C. 20231

Group Art Unit: 2814

Examiner: D. Graybill

Date: October 1, 2001

10/17/01
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PRELIMINARY AMENDMENT

Sir:

Preliminary to initiation of continued prosecution of the
above-identified application, please amend the application as
follows:

IN THE TITLE

Please amend the title of the above-identified application
to: --Methods of Making Compliant Semiconductor Chip Packages--

IN THE CLAIMS

Please cancel claims 1-11 and 21-34.

Insert new claims 35-57 as follows:

35. (New) A method of making a compliant semiconductor
chip package comprising:

providing a semiconductor chip having a contact bearing
surface including a central region bounded by a peripheral
region, wherein the peripheral region of said contact bearing
surface has chip contacts;

EXPRESS MAIL LABEL NUMBER: EL 804525924 US